Microchip Technology - DSPIC33EP64GP502-E/SS Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

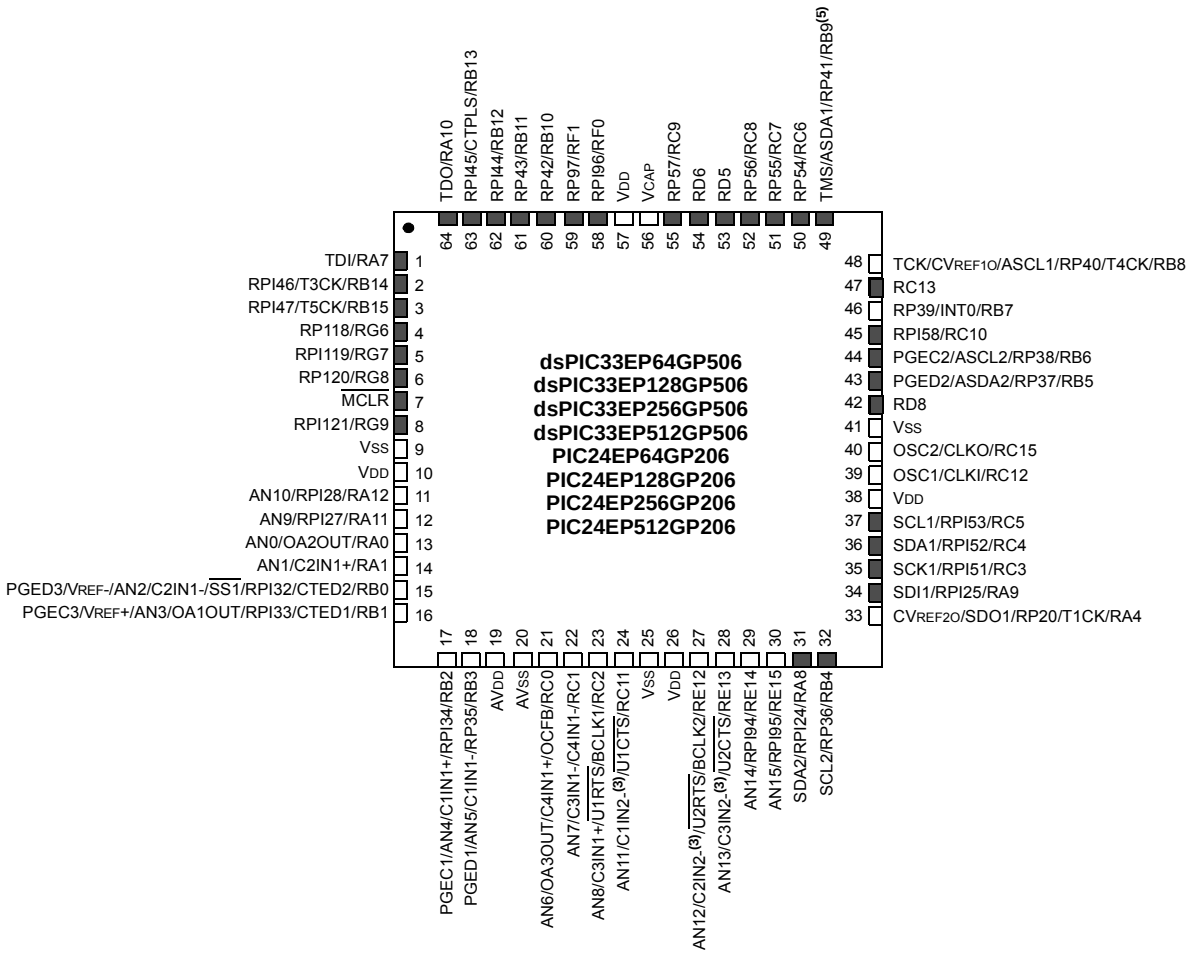
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64gp502-e-ss

Pin Diagrams (Continued)

64-Pin QFN(1,2,3,4)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (Figure 4-6).

Program memory addresses are always word-aligned on the lower word and addresses are incremented, or decremented by two, during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices reserve the addresses between 0x000000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at address, 0x000000, of Flash memory, with the actual address for the start of code at address, 0x000002, of Flash memory.

A more detailed discussion of the Interrupt Vector Tables (IVTs) is provided in **Section 7.1 "Interrupt Vector Table"**.

FIGURE 4-6: PROGRAM MEMORY ORGANIZATION

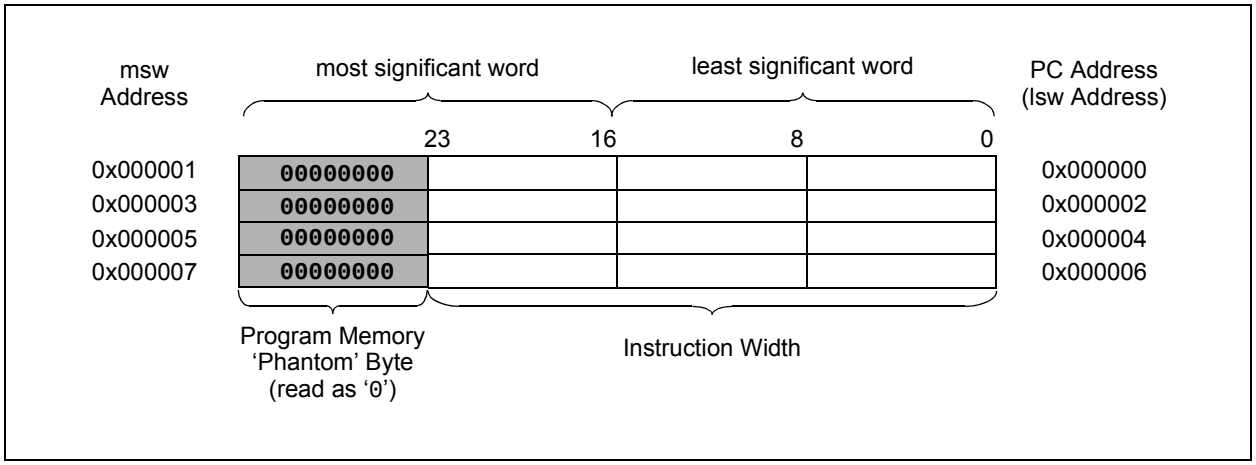


TABLE 4-23: ECAN1 REGISTER MAP WHEN WIN (C1CTRL1<0>) = 1 FOR dsPIC33EPXXXMC/GP50X DEVICES ONLY (CONTINUED)

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1RXF11EID	046E	EID<15:8>								EID<7:0>								xxxx
C1RXF12SID	0470	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF12EID	0472	EID<15:8>								EID<7:0>								xxxx
C1RXF13SID	0474	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF13EID	0476	EID<15:8>								EID<7:0>								xxxx
C1RXF14SID	0478	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF14EID	047A	EID<15:8>								EID<7:0>								xxxx
C1RXF15SID	047C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF15EID	047E	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-45: DMAC REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
DMA0CON	0B00	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA0REQ	0B02	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA0STAL	0B04	STA<15:0>																0000
DMA0STAH	0B06	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA0STBL	0B08	STB<15:0>																0000
DMA0STBH	0B0A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA0PAD	0B0C	PAD<15:0>																0000
DMA0CNT	0B0E	—	—	CNT<13:0>														0000
DMA1CON	0B10	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA1REQ	0B12	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA1STAL	0B14	STA<15:0>																0000
DMA1STAH	0B16	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA1STBL	0B18	STB<15:0>																0000
DMA1STBH	0B1A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA1PAD	0B1C	PAD<15:0>																0000
DMA1CNT	0B1E	—	—	CNT<13:0>														0000
DMA2CON	0B20	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA2REQ	0B22	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA2STAL	0B24	STA<15:0>																0000
DMA2STAH	0B26	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA2STBL	0B28	STB<15:0>																0000
DMA2STBH	0B2A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA2PAD	0B2C	PAD<15:0>																0000
DMA2CNT	0B2E	—	—	CNT<13:0>														0000
DMA3CON	0B30	CHEN	SIZE	DIR	HALF	NULLW	—	—	—	—	—	AMODE<1:0>		—	—	MODE<1:0>		0000
DMA3REQ	0B32	FORCE	—	—	—	—	—	—	—	IRQSEL<7:0>								00FF
DMA3STAL	0B34	STA<15:0>																0000
DMA3STAH	0B36	—	—	—	—	—	—	—	—	STA<23:16>								0000
DMA3STBL	0B38	STB<15:0>																0000
DMA3STBH	0B3A	—	—	—	—	—	—	—	—	STB<23:16>								0000
DMA3PAD	0B3C	PAD<15:0>																0000
DMA3CNT	0B3E	—	—	CNT<13:0>														0000
DMAPWC	0BF0	—	—	—	—	—	—	—	—	—	—	—	—	PWCOL3	PWCOL2	PWCOL1	PWCOL0	0000
DMARQC	0BF2	—	—	—	—	—	—	—	—	—	—	—	—	RQCOL3	RQCOL2	RQCOL1	RQCOL0	0000
DMAPPS	0BF4	—	—	—	—	—	—	—	—	—	—	—	—	PPST3	PPST2	PPST1	PPST0	0000
DMALCA	0BF6	—	—	—	—	—	—	—	—	—	—	—	—	LSTCH<3:0>				000F
DSADRL	0BF8	DSADR<15:0>																0000
DSADRH	0BFA	—	—	—	—	—	—	—	—	DSADR<23:16>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.4 SOFTWARE STACK

The W15 register serves as a dedicated Software Stack Pointer (SSP) and is automatically modified by exception processing, subroutine calls and returns; however, W15 can be referenced by any instruction in the same manner as all other W registers. This simplifies reading, writing and manipulating of the Stack Pointer (for example, creating stack frames).

Note: To protect against misaligned stack accesses, W15<0> is fixed to '0' by the hardware.

W15 is initialized to 0x1000 during all Resets. This address ensures that the SSP points to valid RAM in all dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, and permits stack availability for non-maskable trap exceptions. These can occur before the SSP is initialized by the user software. You can reprogram the SSP during initialization to any location within Data Space.

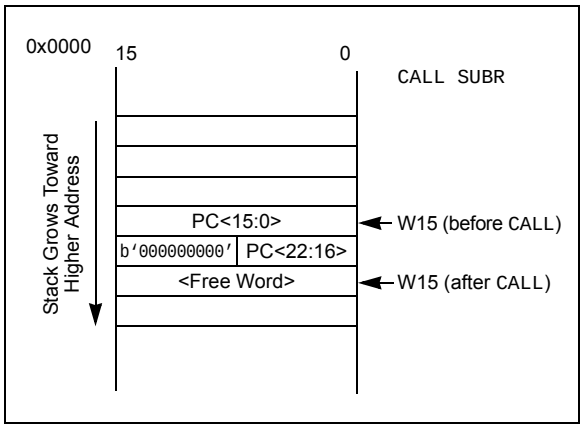
The Software Stack Pointer always points to the first available free word and fills the software stack working from lower toward higher addresses. Figure 4-19 illustrates how it pre-decrements for a stack pop (read) and post-increments for a stack push (writes).

When the PC is pushed onto the stack, PC<15:0> are pushed onto the first available stack word, then PC<22:16> are pushed into the second available stack location. For a PC push during any CALL instruction, the MSB of the PC is zero-extended before the push, as shown in Figure 4-19. During exception processing, the MSB of the PC is concatenated with the lower 8 bits of the CPU STATUS Register, SR. This allows the contents of SRL to be preserved automatically during interrupt processing.

Note 1: To maintain system Stack Pointer (W15) coherency, W15 is never subject to (EDS) paging, and is therefore restricted to an address range of 0x0000 to 0xFFFF. The same applies to the W14 when used as a Stack Frame Pointer (SFA = 1).

2: As the stack can be placed in, and can access X and Y spaces, care must be taken regarding its use, particularly with regard to local automatic variables in a C development environment

FIGURE 4-19: CALL STACK FRAME



4.8.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the Program Space without going through Data Space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a Program Space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to Data Space addresses. Program memory can thus be regarded as two 16-bit-wide word address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

Two table instructions are provided to move byte or word-sized (16-bit) data to and from Program Space. Both function as either byte or word operations.

- TBLRDL (Table Read Low):
  - In Word mode, this instruction maps the lower word of the Program Space location (P<15:0>) to a data address (D<15:0>)
  - In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.
- TBLRDH (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. The 'phantom' byte (D<15:8>) is always '0'.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address in the TBLRDL instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a Program Space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user application and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

FIGURE 4-23: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS

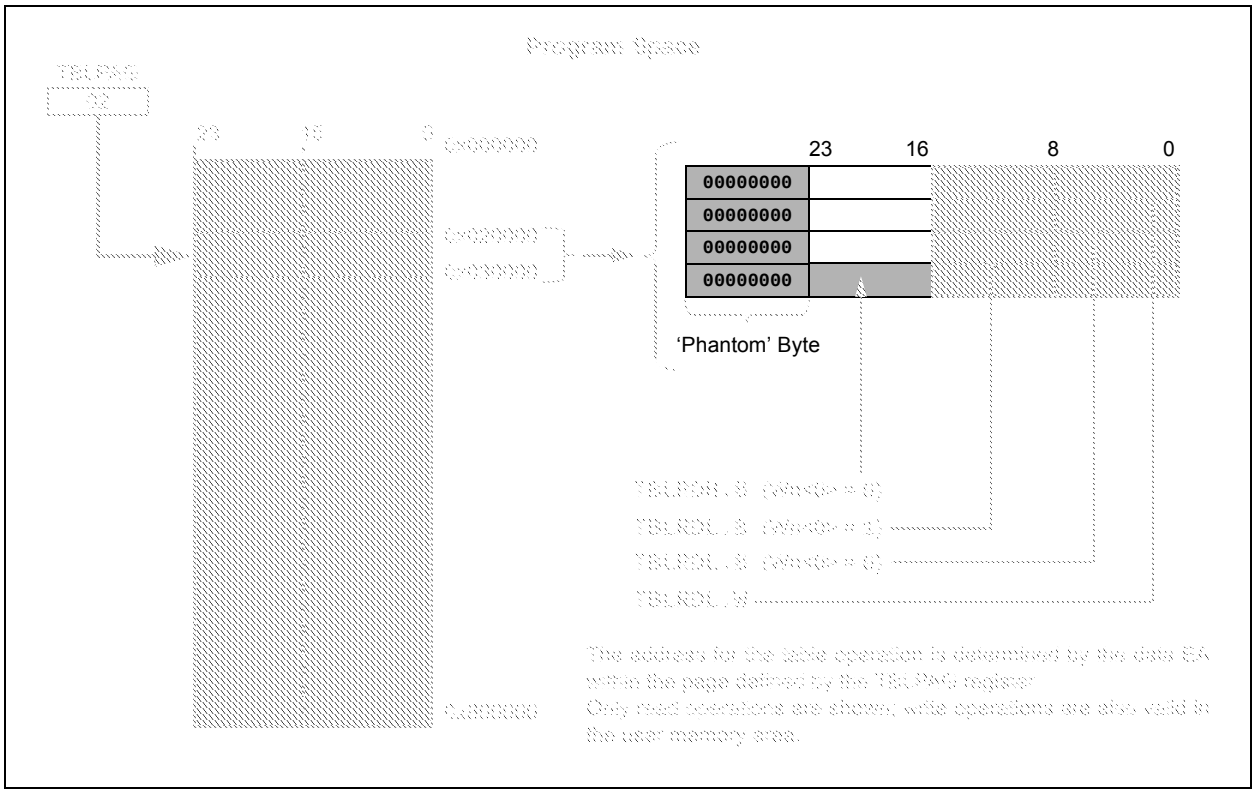


TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Notes
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	xx	101	**1**
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	**1**
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	**1**
Fast RC Oscillator (FRC) with Divide-by-N and PLL (FRCPLL)	Internal	xx	001	**1**
Fast RC Oscillator (FRC)	Internal	xx	000	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

9.2 Oscillator Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

9.2.1 KEY RESOURCES

- **"Oscillator"** (DS70580) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 21-16: CxRXFnSID: ECANx ACCEPTANCE FILTER n STANDARD IDENTIFIER REGISTER (n = 0-15)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	EXIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Message address bit, SIDx, must be '1' to match filter
0 = Message address bit, SIDx, must be '0' to match filter

bit 4 **Unimplemented:** Read as '0'

bit 3 **EXIDE:** Extended Identifier Enable bit
If MIDE = 1:
1 = Matches only messages with Extended Identifier addresses
0 = Matches only messages with Standard Identifier addresses
If MIDE = 0:
Ignores EXIDE bit.

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Message address bit, EIDx, must be '1' to match filter
0 = Message address bit, EIDx, must be '0' to match filter

REGISTER 24-8: PTGC1LIM: PTG COUNTER 1 LIMIT REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC1LIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGC1LIM<15:0>:** PTG Counter 1 Limit Register bits
May be used to specify the loop count for the PTGJMPC1 Step command or as a limit register for the General Purpose Counter 1.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

REGISTER 24-9: PTGHOLD: PTG HOLD REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGHOLD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGHOLD<15:0>:** PTG General Purpose Hold Register bits
Holds user-supplied data to be copied to the PTGTxLIM, PTGCxLIM, PTGSDLIM or PTGL0 registers with the PTGCOPY command.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2 OR 3) (CONTINUED)

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
- 11 = Trigger/event/interrupt generated on any change of the comparator output (while CEVT = 0)
- 10 = Trigger/event/interrupt generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)
  - If CPOL = 1 (inverted polarity):
    Low-to-high transition of the comparator output.
  - If CPOL = 0 (non-inverted polarity):
    High-to-low transition of the comparator output.
- 01 = Trigger/event/interrupt generated only on low-to-high transition of the polarity-selected comparator output (while CEVT = 0)
  - If CPOL = 1 (inverted polarity):
    High-to-low transition of the comparator output.
  - If CPOL = 0 (non-inverted polarity):
    Low-to-high transition of the comparator output
- 00 = Trigger/event/interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Reference Select bit (V_{IN+} input)(1)
- 1 = V_{IN+} input connects to internal CV_{REFIN} voltage(2)
- 0 = V_{IN+} input connects to CxIN1+ pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Op Amp/Comparator Channel Select bits(1)
- 11 = Unimplemented
- 10 = Unimplemented
- 01 = Inverting input of the comparator connects to the CxIN2- pin(2)
- 00 = Inverting input of the op amp/comparator connects to the CxIN1- pin

Note 1: Inputs that are selected and not available will be tied to V_{SS}. See the **"Pin Diagrams"** section for available inputs for each package.

2: This output is not available when OPMODE (CMxCON<10>) = 1.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
25	DAW	DAW	Wn	Wn = decimal adjust Wn	1	1	C
26	DEC	DEC	f	f = f – 1	1	1	C,DC,N,OV,Z
		DEC	f,WREG	WREG = f – 1	1	1	C,DC,N,OV,Z
		DEC	Ws,Wd	Wd = Ws – 1	1	1	C,DC,N,OV,Z
27	DEC2	DEC2	f	f = f – 2	1	1	C,DC,N,OV,Z
		DEC2	f,WREG	WREG = f – 2	1	1	C,DC,N,OV,Z
		DEC2	Ws,Wd	Wd = Ws – 2	1	1	C,DC,N,OV,Z
28	DISI	DISI	#lit14	Disable Interrupts for k instruction cycles	1	1	None
29	DIV	DIV.S	Wm,Wn	Signed 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.SD	Wm,Wn	Signed 32/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.U	Wm,Wn	Unsigned 16/16-bit Integer Divide	1	18	N,Z,C,OV
		DIV.UD	Wm,Wn	Unsigned 32/16-bit Integer Divide	1	18	N,Z,C,OV
30	DIVF	DIVF	Wm,Wn(1)	Signed 16/16-bit Fractional Divide	1	18	N,Z,C,OV
31	DO	DO	#lit15,Expr(1)	Do code to PC + Expr, lit15 + 1 times	2	2	None
		DO	Wn,Expr(1)	Do code to PC + Expr, (Wn) + 1 times	2	2	None
32	ED	ED	Wm*Wm,Acc,Wx,Wy,Wxd(1)	Euclidean Distance (no accumulate)	1	1	OA,OB,OAB, SA,SB,SAB
33	EDAC	EDAC	Wm*Wm,Acc,Wx,Wy,Wxd(1)	Euclidean Distance	1	1	OA,OB,OAB, SA,SB,SAB
34	EXCH	EXCH	Wns,Wnd	Swap Wns with Wnd	1	1	None
35	FBCL	FBCL	Ws,Wnd	Find Bit Change from Left (MSb) Side	1	1	C
36	FF1L	FF1L	Ws,Wnd	Find First One from Left (MSb) Side	1	1	C
37	FF1R	FF1R	Ws,Wnd	Find First One from Right (LSb) Side	1	1	C
38	GOTO	GOTO	Expr	Go to address	2	4	None
		GOTO	Wn	Go to indirect	1	4	None
		GOTO.L	Wn	Go to indirect (long address)	1	4	None
39	INC	INC	f	f = f + 1	1	1	C,DC,N,OV,Z
		INC	f,WREG	WREG = f + 1	1	1	C,DC,N,OV,Z
		INC	Ws,Wd	Wd = Ws + 1	1	1	C,DC,N,OV,Z
40	INC2	INC2	f	f = f + 2	1	1	C,DC,N,OV,Z
		INC2	f,WREG	WREG = f + 2	1	1	C,DC,N,OV,Z
		INC2	Ws,Wd	Wd = Ws + 2	1	1	C,DC,N,OV,Z
41	IOR	IOR	f	f = f .IOR. WREG	1	1	N,Z
		IOR	f,WREG	WREG = f .IOR. WREG	1	1	N,Z
		IOR	#lit10,Wn	Wd = lit10 .IOR. Wd	1	1	N,Z
		IOR	Wb,Ws,Wd	Wd = Wb .IOR. Ws	1	1	N,Z
		IOR	Wb,#lit5,Wd	Wd = Wb .IOR. lit5	1	1	N,Z
42	LAC	LAC	Wso,#Slit4,Acc	Load Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
43	LNK	LNK	#lit14	Link Frame Pointer	1	1	SFA
44	LSR	LSR	f	f = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	f,WREG	WREG = Logical Right Shift f	1	1	C,N,OV,Z
		LSR	Ws,Wd	Wd = Logical Right Shift Ws	1	1	C,N,OV,Z
		LSR	Wb,Wns,Wnd	Wnd = Logical Right Shift Wb by Wns	1	1	N,Z
		LSR	Wb,#lit5,Wnd	Wnd = Logical Right Shift Wb by lit5	1	1	N,Z
45	MAC	MAC	Wm*Wn,Acc,Wx,Wxd,Wy,Wyd,AWB(1)	Multiply and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB
		MAC	Wm*Wm,Acc,Wx,Wxd,Wy,Wyd(1)	Square and Accumulate	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})(1)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (I_{DOZE})(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

Note 1: I_{DOZE} is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all I_{DOZE} measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

FIGURE 30-13: QEI MODULE INDEX PULSE TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

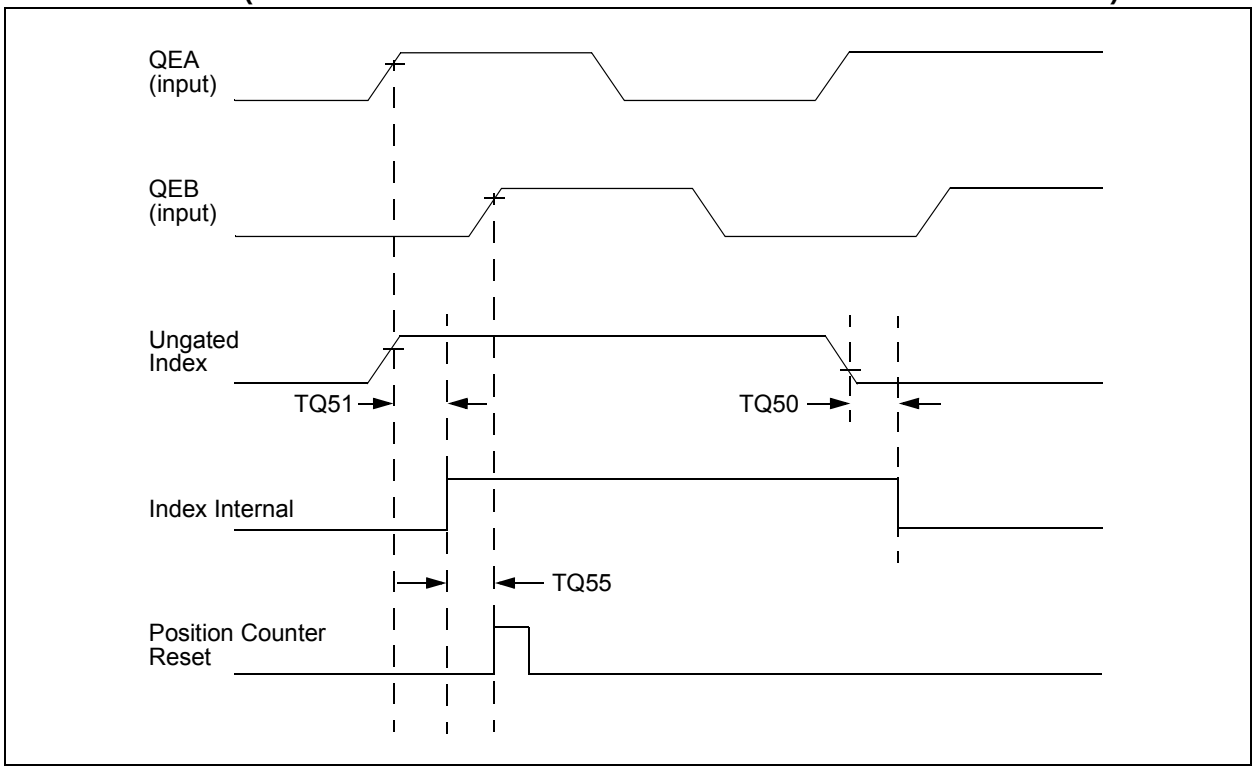


TABLE 30-32: QEI INDEX PULSE TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Max.**	**Units**	**Conditions**
TQ50	TqiL	Filter Time to Recognize Low, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ51	TqiH	Filter Time to Recognize High, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ55	Tqidxr	Index Pulse Recognized to Position Counter Reset (ungated index)	3 TCY	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Alignment of index pulses to QEA and QEB is shown for position counter Reset timing only. Shown for forward direction only (QEA leads QEB). Same timing applies for reverse direction (QEA lags QEB) but index pulse recognition occurs on the falling edge.

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: VOH – 4x DRIVER PINS

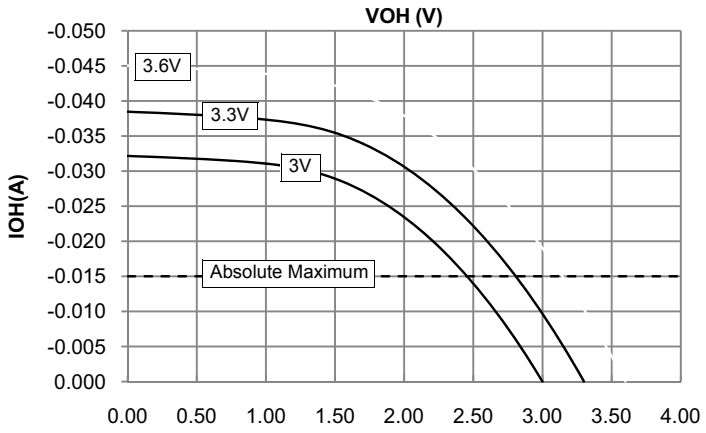


FIGURE 32-2: VOH – 8x DRIVER PINS

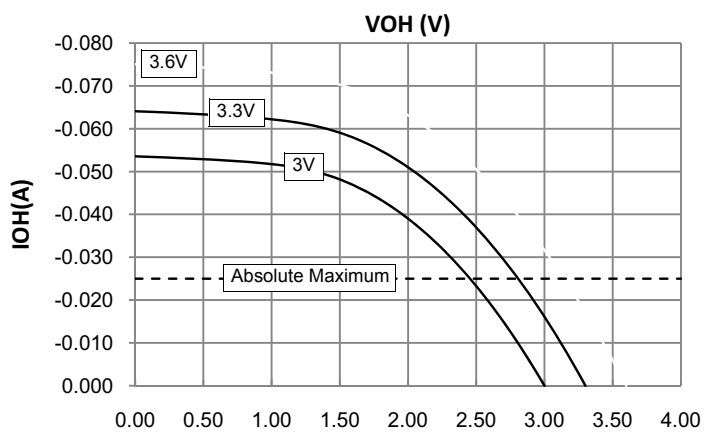


FIGURE 32-3: VOL – 4x DRIVER PINS

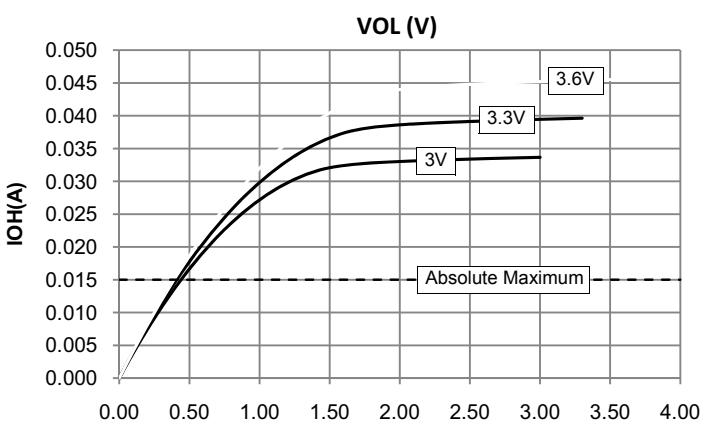
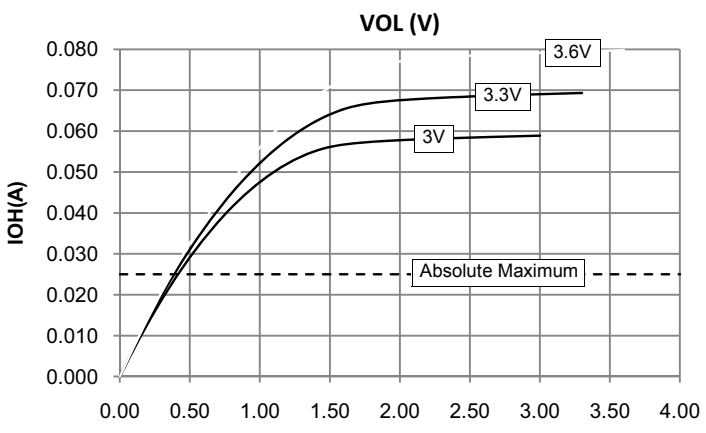


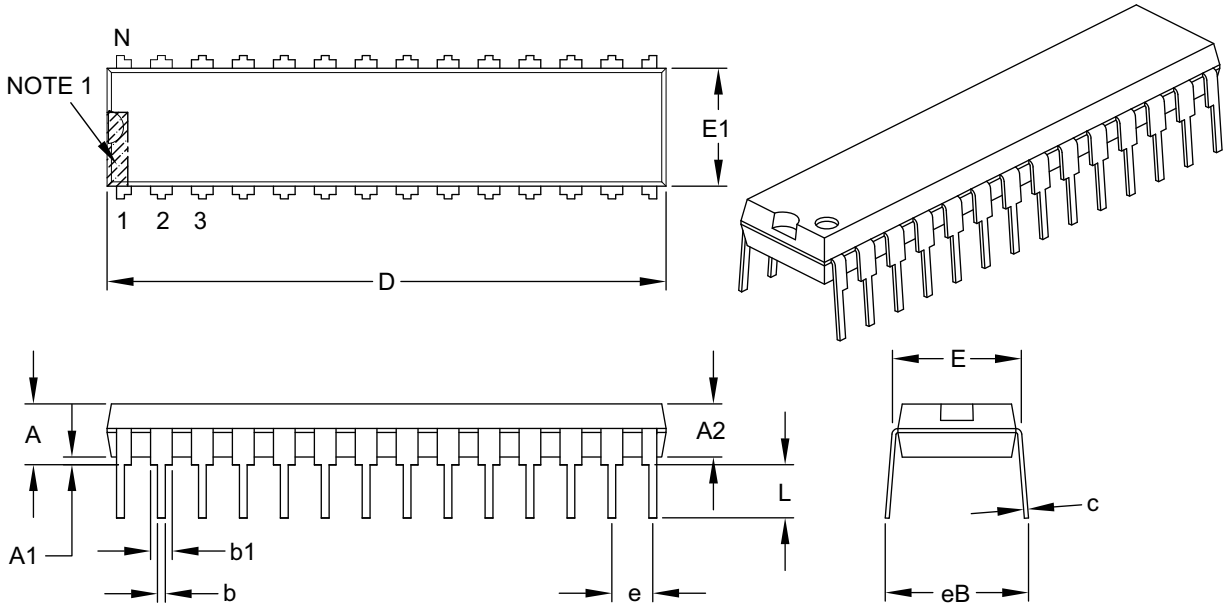
FIGURE 32-4: VOL – 8x DRIVER PINS



33.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

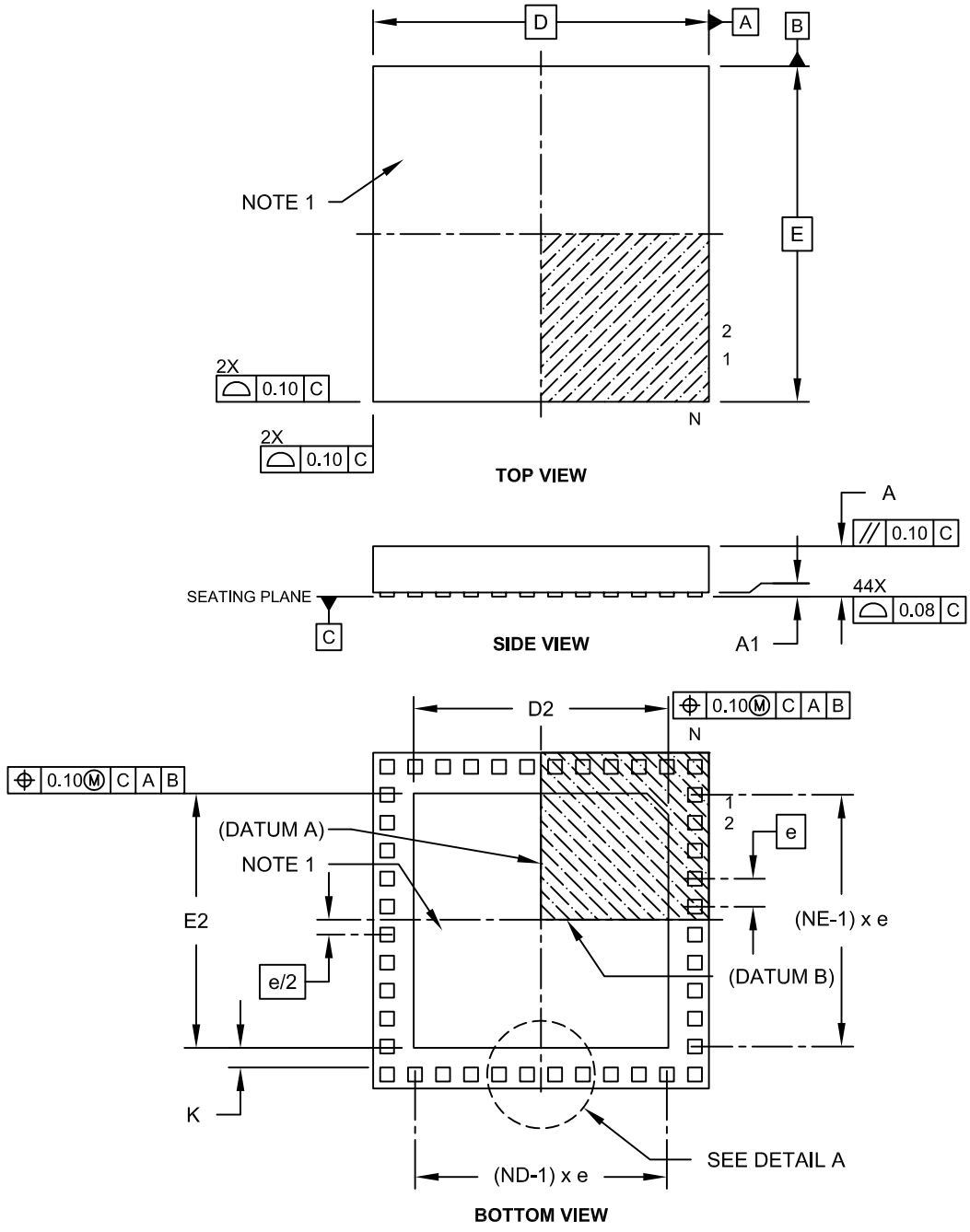
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-157C Sheet 1 of 2

INDEX

A

B

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